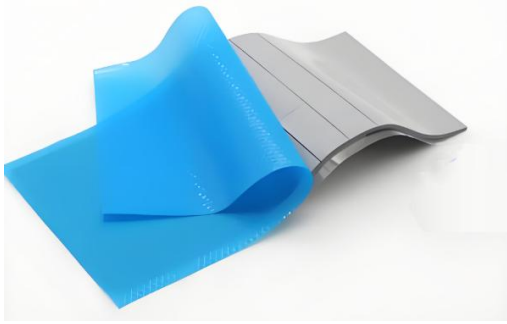


# K-HC 500X-GY Series EMI Absorbing and Thermally Conductive Silicone Pad

**TDS**



The K-HC 500X is a specially engineered EMI absorbing thermal pad designed to meet heat dissipation requirements where specific hardness is not critical. Its flexibility accommodates most press-fit assembly demands, demonstrating low thermal resistance and effective absorption properties for eliminating electromagnetic interference (EMI). It displaces air between components and PCBs, thoroughly filling various rough surfaces. The product features inherent tackiness. By default, it has a substrate-free construction, but can be customized with a substrate, such as backing with 3M adhesive, fiberglass, or other processes to fulfill specific application requirements.

### Product Characteristics:

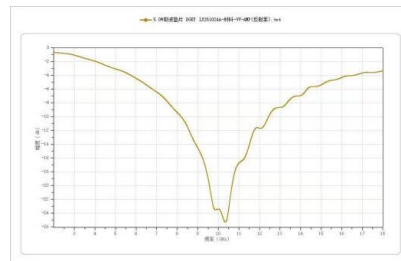
- Thermal Conductivity = 5.0 W/m-K
- Conforms easily, ultra-low hardness, suitable for low clamping pressure applications.
- Flame retardant rating: V-0; Environmental compliance: ROHS.
- Eliminates electromagnetic signal interference.

### Typical Applications:

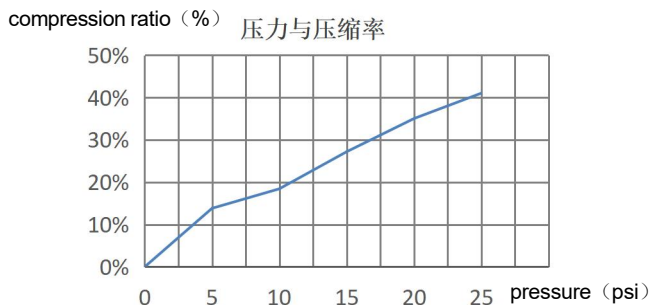
- Telecommunications industry.
- Computers and peripherals; Power converters.
- Interface between semiconductors/magnetic components and heat sinks.
- Areas requiring heat transfer, such as frames, chassis, or other thermal conductors.

Symbol properties		
properties of products	test value	test method
Material	Thermally Conductive & Magnetic Material	—
Color	Gray	Visual
Thickness range (mm)	0.5 -10.0	ASTM D374
Density (g/cm <sup>3</sup> )	4.2±0.2	ASTM D792
Hardness (Shore OO)	30-70	ASTM D2240
EMI Absorption Performance (dB / 1-3mm thickness)	-25±10	GJB5239-2004
Weight loss (%)	≤1	@200℃ 200H
Temperature resistance range (°C)	-40 ~ 150	EN344
Weight loss (%)	≤1	200℃ 4H
Fire Rating	V0	UL 94
Thermal conductivity (W/m-K)	5.0±0.3	ASTM D5470

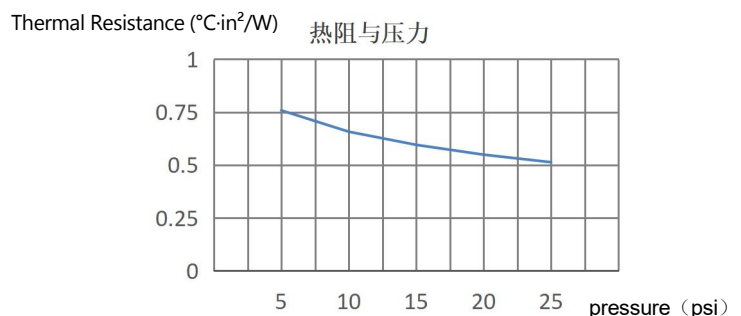
Thickness tolerance: ≤ ±10% of nominal thickness, Storage conditions: Temperature 5°C to 38°C, Humidity 35% to 75% RH, Absorption value at 1.5mm thickness.



### Compression Curve (at 2.0mm thickness)



### Thermal Resistance Curve (at 2.0mm thickness)



**Note:** Please refer to the MSDS report for the safety data of the product. The data in this paper are obtained under laboratory conditions. Due to the differences in the conditions of use, users need to refer to these data and conditions of use for analysis and testing. The company does not guarantee the sale of this product and the use of the company's products under specific conditions of the problem, does not assume any direct, indirect or accidental loss liability. Users can contact the technical service department across the company if they encounter any problems in the use process.